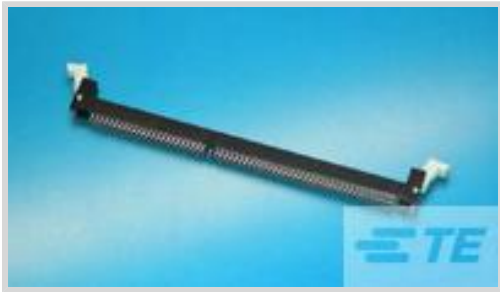




Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

Termination Method to PCB: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM Sockets \(13\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board

Configuration Features

Number of Positions	240
Module Orientation	Vertical

Body Features

Ejector Type	Standard
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Contact Features

Contact Current Rating (Max)	.75 A
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Termination Features

Termination Method to PCB	Through Hole - Solder
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Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Boardlock

Housing Features



Centerline (Pitch)	1 mm[.039 in]
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Dimensions

Row-to-Row Spacing	1.9 mm[.075 in]
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Usage Conditions

Operating Temperature Range	-55 – 155 °C[-67 – 311 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Method	Box & Tray, Tray
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Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

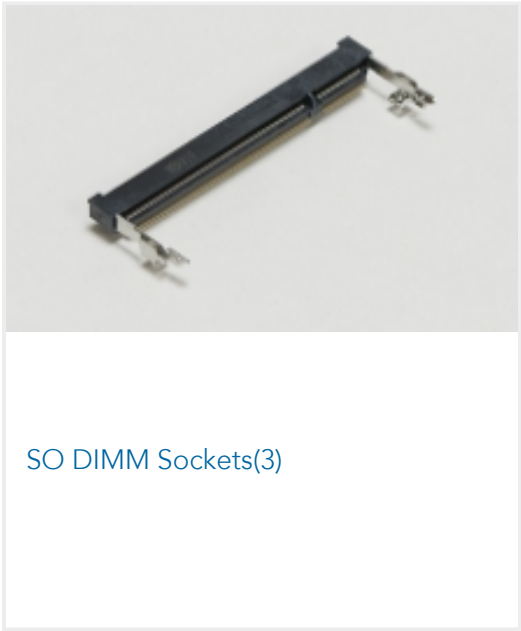
Compatible Parts



Also in the Series | [DDR3 DIMM](#)



Also in the Series | [DDR3 SO DIMM](#)



Customers Also Bought





Documents

Product Drawings

VERTICAL DDR3 DIMM, 240 POSITION

English

CAD Files

Customer View Model

ENG_CVM_CVM_4-1932000-8_F.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_4-1932000-8_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_4-1932000-8_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

6-1773457-3_DDR3_DIMM_SOCKETS

Product Specifications

Product Specification

English

Agency Approvals

Agency Approval Document

English